

27th IEEE International System-on-Chip Conference

September 2-5, 2014

Planet Hollywood Resort, Las Vegas, NV, USA



Committee

General Chair

Kaijian Shi
Cadence Design Systems

Technical Program Chair

Thomas Buechner

IBM

TPC Co-Chair

Danella Zhao
Univ. of Louisiana at Lafayette

Financial/Publication Chair

Ramalingam Sridhar

SUNY at Buffalo

Tutorial Chair

Yuejian Wu

Infinera

Publicity Chair

Andrew Marshall
University of Texas at Dallas

Sponsorship/Exhibition Chair

Karan Bhatia

Texas Instruments

Local OC Chair

Venki Muthukumar
Univ. of Nevada Las Vegas

Steering Committee Chair

Norbert Schuhmann

Fraunhofer IIS

Europe Liaison

Sakir Sezer
Queen's University, Belfast

Asia-Pacific Liaison

Sao-Jie Chen
National Taiwan University

Industrial Liaison

Nagi Naganathan
LSI Corp.



Call For Papers - Submission Deadline Extension

The IEEE SoC Conference (SOCC) is a premier forum for sharing advances in SoC technologies and applications in the areas of digital systems, circuit architectures, computing platforms, design methods, automations, test, and emerging technologies. SOCC2014 offers a four-day technical program, which features:

◆ **Keynote and plenary speakers** - **Tom Beckley** (Sr. VP of R&D for Custom IC and Simulation, Cadence) “The Internet of Every-Thing: EDA Perspectives”, **Scott Runner** (VP of Advanced Methodologies and Low-Power Design, Qualcomm) “SoCs for Mobile Applications: Systems from 0 MPH to over 100 MPH”, **J. Thomas Pawlowski** (Fellow and Chief Technologist, Micron Technology, Inc.) “The Future of Memory/Logic Technologies and Computing System Architectures”, and more to come;

◆ **SoCC Student Grant** sponsored by IEEE CASS Outreach Initiative, including Student Travel Grant and Student Tutorial School Grant;

◆ A new “**Design Track**” to encourage engineers to present their work and share their knowledge and experience in the development of SoC designs; and

◆ A high quality **social events** program, including a Las Vegas show, conference banquet, and a tour of the cavernous power house of Hoover Dam hydro-electric plant.

Contact us at info@ieee-socc.org, follow us on [twitter@ieee_socc](https://twitter.com/ieee_socc), and join us in LinkedIn SOCC Group.

Submission of Papers and Workshop/Tutorial/Special Session Proposals

Online paper submissions are in *pdf* format, limited to **six** double-column IEEE format pages. Paper submissions will go through a double-blind peer review process. The SOCC proceedings will be submitted to IEEE *Xplore*®. Workshop/tutorial proposals with title, a one-page summary, and speaker's short bio are submitted to the Tutorial Chair. **Special session** proposals may include title, topic rationale, organizer's short bio, and a list of contributed papers, which are submitted to the TPC Chairs. “**SoC Design Track**” submissions require a two-page extended abstract which will be published on the SOCC website and in the program. For detailed formatting instructions and submission guidelines, please refer to www.ieee-socc.org.

SOCC Areas of Interest

Papers are invited which address new and previously unpublished results in the areas:

- ◆ Analog and Mixed-Signal Circuits and Systems
- ◆ Biomedical Circuits and Systems
- ◆ Wireline and Wireless Communication Circuits and Systems
- ◆ Digital Signal Processing (DSP) Circuits and Systems
- ◆ Low-Power, “Green” Circuits, Systems, and Design Methodologies
- ◆ Embedded Systems, Multi/Many Core Systems & Embedded Memory Technologies
- ◆ Network on Chip (NoC), Interconnects, and 3D-IC
- ◆ Reconfigurable and Programmable Circuits and Systems
- ◆ System Level Design Methodology and Tools
- ◆ Design for Testability and Manufacturability
- ◆ Design Verification
- ◆ Computing Platform Architectures

Key Dates

Special session/Workshop/tutorial proposal due:

April 14th, 2014 (Extended)

Regular paper submission deadline:

May 2nd, 2014 (Final)

SoC Design Track extended abstract due:

May 2nd, 2014 (Final)

Notification of acceptance:

June 10th, 2014

Final camera-ready paper due:

June 30th, 2014